10/008,636

30 March 2004

30 Marc			DB	Time stamp
L Number	Hits	Search Text	USPAT;	2004/03/26
-	6	353325.apn. 409690.apn. 354649.apn. 823948.apn.	US-PGPUB;	11:55
		998142.apn. 717927.apn.	EPO; JPO;	11.55
			DERWENT;	
			IBM_TDB	2004/02/17
_	3	6309524.pn. 6080291.pn. 6527925.pn.	USPAT	2004/03/17
			1100.00	14:23
-	3	5227041.pn. 6139712.pn. 6309524.pn.	USPAT	2004/03/17
				14:23
-	130	205/\$.ccls. and tilt\$5 and immers\$5	USPAT;	2004/03/25
			U5-PGPUB;	08:30
			EPO; JPO;	
			DERWENT;	
			IBW_TDB	
_	101	205/\$.ccls. and tilt\$5 and immers\$5	USPAT	2004/03/25
				08:30
_	39	204/\$.ccls. and cantilevered and arcuate	USPAT;	2004/03/25
			US-PGPUB;	15:16
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	8	204/\$.ccls. and cantilevered.clm. and arcuate.clm.	USPAT;	2004/03/25
		20 17 4 .0010. 2.112 04.17 110 10 10 10 10 10 10 10 10 10 10 10 10	US-PGPUB;	15:16
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	78	US-4137867-\$.DID. OR US-4246088-\$.DID. OR	USPAT;	2004/03/26
	'6	US-4259166-\$.DID. OR US-4304641-\$.DID. OR	US-PGPUB;	14:19
		US-4341629-\$.DID. OR US-4422915-\$.DID. OR	EPO; JPO;	
		US-4466864-\$.DID. OR US-4576685-\$.DID. OR	DERWENT;	
		US-4685414-\$.DID. OR US-4913085-\$.DID. OR	IBM_TDB	
		US-5135636-\$.DID. OR US-5139818-\$.DID. OR		
		US-5227041-\$.DID. OR US-5271953-\$.DID. OR		
	1	US-5227041-\$.DID. OR US-5271933-\$.DID. OR US-5310580-\$.DID. OR US-5344491-\$.DID. OR		
		US-5310360-\$.DID. OR US-5344491-\$.DID. OR US-5389496-\$.DID. OR US-5441629-\$.DID. OR		
		US-5389496-\$.DID. OR US-5447615-\$.DID. OR US-5443707-\$.DID. OR US-5447615-\$.DID. OR		
		US-5443707-\$.DID. OR US-5447615-\$.DID. OR US-5522975-\$.DID. OR US-5550315-\$.DID. OR		
		US-5597460-\$.DID. OR US-5597836-\$.DID. OR		
		US-5985126-\$.DID. OR US-5609239-\$.DID. OR		
		US-5670034-\$.DID. OR US-5744019-\$.DID. OR		
		US-5747098-\$.DID. OR US-5776327-\$.DID. OR		
		US-5788829-\$.DID. OR US-5843296-\$.DID. OR		
		US-5904827-\$.DID. OR US-5932077-\$.DID. OR		
		US-6001235-\$.DID. OR US-6080291-\$.DID. OR		
		US-6139712-\$.DID. OR US-6156167-\$.DID. OR		
		US-6303010-\$.DID. OR US-6309520-\$.DID. OR		
		US-6309524-\$.DID.		

	41	US-4137867-\$.DID. OR US-4246088-\$.DID. OR	USPAT	2004/03/26
-	71	US-4259166-\$.DID. OR US-4304641-\$.DID. OR	OSFAT	12:05
		U5-4341629-\$.DID. OR US-4422915-\$.DID. OR		12.05
		·		
		US-4466864-\$.DID. OR US-4576685-\$.DID. OR		
		US-4685414-\$.DID. OR US-4913085-\$.DID. OR		
	,	US-5135636-\$.DID. OR US-5139818-\$.DID. OR		
		US-5227041-\$.DID. OR US-5271953-\$.DID. OR		
		US-5310580-\$.DID. OR US-5344491-\$.DID. OR		
		U5-5389496-\$.DID. OR U5-5441629-\$.DID. OR		
		US-5443707-\$.DID. OR US-5447615-\$.DID. OR		
		US-5522975-\$.DID. OR US-5550315-\$.DID. OR		
		US-5597460-\$.DID. OR US-5597836-\$.DID. OR		
		US-5985126-\$.DID. OR US-5609239-\$.DID. OR		
		US-5670034-\$.DID. OR US-5744019-\$.DID. OR		
		US-5747098-\$.DID. OR US-5776327-\$.DID. OR		
		US-5788829-\$.DID. OR US-5843296-\$.DID. OR		
		US-5904827-\$.DID. OR US-5932077-\$.DID. OR		
		US-6001235-\$.DID. OR US-6080291-\$.DID. OR		
		US-6139712-\$.DID. OR US-6156167-\$.DID. OR		
		U5-6303010-\$.DID. OR US-6309520-\$.DID. OR		
		US-6309524-\$.DID.		
_	42	US-4137867-\$.DID. OR US-4246088-\$.DID. OR	USPAT	2004/03/26
	,-	US-4259166-\$.DID. OR US-4304641-\$.DID. OR		12:05
		U5-4341629-\$.DID. OR U5-4422915-\$.DID. OR		12.03
		US-4466864-\$.DID. OR US-4576685-\$.DID. OR		
		U5-4685414-\$.DID. OR US-4913085-\$.DID. OR		
		US-5135636-\$.DID. OR US-5139818-\$.DID. OR		
		US-5227041-\$.DID. OR US-5271953-\$.DID. OR		
		US-5310580-\$.DID. OR US-5344491-\$.DID. OR		
		US-5389496-\$.DID. OR US-5441629-\$.DID. OR		
		US-5443707-\$.DID. OR US-5447615-\$.DID. OR		
		US-5522975-\$.DID. OR US-5550315-\$.DID. OR		
		US-5597460-\$.DID. OR US-5597836-\$.DID. OR		
		U5-5985126-\$.DID. OR US-5609239-\$.DID. OR		
	-	US-5670034-\$.DID. OR US-5744019-\$.DID. OR		
		US-5747098-\$.DID. OR US-5776327-\$.DID. OR		
		US-5788829-\$.DID. OR US-5843296-\$.DID. OR		
		US-5904827-\$.DID. OR US-5932077-\$.DID. OR		
		US-6001235-\$.DID. OR US-6080291-\$.DID. OR		
		US-6139712-\$.DID. OR US-6156167-\$.DID. OR		
		US-6303010-\$.DID. OR US-6309520-\$.DID. OR		
]		US-6309524-\$.DID. OR US-6645356-\$.did.		·
-	9727	204/\$.ccls. and (microelectr\$7 or semiconductor or	USPAT;	2004/03/29
		wafer)	US-PGPUB,	11:47
			EPO; JPO;	
			DERWENT;	
	İ		IBM_TDB	
-	290	204/\$.ccls. and (contact adj (assembly or ring))	USPAT;	2004/03/26
	_, _	ין אויין	US-PGPUB;	14:31
			EPO; JPO;	
			DERWENT;	,
			IBM_TDB	
L	l		TOM_IOR	<u> </u>

_	152	(204/\$.ccls. and (microelectr\$7 or semiconductor or	USPAT;	2004/03/26
		wafer)) and (204/\$.ccls. and (contact adj (assembly	U5-PGPUB;	15:12
		or ring)))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	•
_	7	("4269686" "5429733" "5447615" "5779492"	USPAT	2004/03/26
·	·	"5833820" "5871626" "6056869").PN.		14:36
_	138	(204/\$.ccls. and (contact adj (assembly or ring))) not	USPAT;	2004/03/26
		((204/\$.ccls. and (microelectr\$7 or semiconductor or	US-PGPUB;	15:25
·		wafer)) and (204/\$.ccls. and (contact adj (assembly	EPO; JPO;	
		or ring))))	DERWENT;	
			IBM_TDB	
_	402	(204/\$.ccls. and (microelectr\$7 or semiconductor or	USPAT;	2004/03/29
		wafer)) and finger	US-PGPUB;	10:42
			EPO; JPO;	
		·	DERWENT;	
		. ,	IBW_TDB	
-	3620	204/\$.ccls. and ((contact or pin or finger) with	USPAT;	2004/03/29
		(dielectric or insulat\$4 or nonconduct\$3))	US-PGPUB;	11:50
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1435	(204/\$.ccls. and ((contact or pin or finger) with	USPAT;	2004/03/29
		(dielectric or insulat\$4 or nonconduct\$3))) and	US-PGPUB;	11:50
		(microelectr\$7 or semiconductor or wafer)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	614	((204/\$.ccls. and ((contact or pin or finger) with	USPAT;	2004/03/29
		(dielectric or insulat\$4 or nonconduct\$3))) and	US-PGPUB;	11:50
		(microelectr\$7 or semiconductor or wafer)) and	EPO; JPO;	
	;	(electroplat\$5 or electrodeposit\$5 or	DERWENT;	
		electrochemical\$5 or (electro adj plat\$5) or (electro	IBM_TDB	
		adj deposit\$5) or electroetch\$5 or (electro adj		
		etch\$5) or (electro adj polish\$5) or		
	2000	electropolish\$5)		
-	2098	204/\$.ccls. and ((contact or pin or finger) near5	USPAT;	2004/03/29
		(dielectric or insulat\$4 or nonconduct\$3))	US-PGPUB;	11:50
			EPO; JPO;	
			DERWENT;	
	915	(201/\$ sole and ((sontact on nin on fine)	IBM_TDB	2004/02/20
-	910	(204/\$.ccls. and ((contact or pin or finger) near5 (dielectric or insulat\$4 or nonconduct\$3))) and	USPAT;	2004/03/29 11:50
		(microelectr\$7 or semiconductor or wafer)	US-PGPUB; EPO; JPO;	11.50
		(microelectify of semiconductor of water)	DERWENT:	
			IBM_TDB	
_	396	((204/\$.ccls. and ((contact or pin or finger) near5	USPAT;	2004/03/29
		(dielectric or insulat\$4 or nonconduct\$3))) and	US-PGPUB;	11:57
		(microelectr\$7 or semiconductor or wafer)) and	EPO; JPO;	
		(electroplat\$5 or electrodeposit\$5 or	DERWENT,	
		electrochemical\$5 or (electro adj plat\$5) or (electro	IBM_TDB	
		adj deposit\$5) or electroetch\$5 or (electro adj		
		etch\$5) or (electro adj polish\$5) or		
		electropolish\$5)		
<u> </u>			· · · · · · · · · · · · · · · · · · ·	

-	10	204/\$.ccls. and bleck.in.	USPAT;	2004/03/29
			U5-PGPUB;	13:48
			EPO; JPO;	
			DERWENT;	
		•	IBW_LDB	·
-	2	6527925.pn.	USPAT;	2004/03/29
			US-PGPUB;	13:48
		·	EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	821	204/224r.ccls.	USPAT;	2004/03/30
			US-PGPUB;	08:50
			EPO; JPO;	•
			DERWENT;	
			IBM_TDB	
_	1275	204/280,286.1,297.01,297.06,297.07,297.08,297.09,2	9715297:14.ccls	. 2004/03/30
			US-PGPUB;	08:55
			EPO; JPO;	
·	·		DERWENT;	
		·	IBM_TDB	
_	2022	204/224r.ccls.	USPAT;	2004/03/30
		204/280,286.1,297.01,297.06,297.07,297.08,297.09,2	9715, 2927 P.UBccls	. 08:57
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	88	(204/224r.ccls.	USPAT;	2004/03/30
		204/280,286.1,297.01,297.06,297.07,297.08,297.09,2	97.15,2927.11Bccls	.)09:28
		and ((post or turret or protrusion or extension) with	EPO; JPO;	
		(contact or finger or conductor))	DERWENT;	
·			IBM_TDB	
-	7	(("6699373") or ("6309520") or ("6334937") or	USPAT;	2004/03/30
1		("6309524") or ("6645356")).PN.	US-PGPUB;	15:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	5	(("6699373") or ("6309520") or ("6334937") or	USPAT	2004/03/30
		("6309524") or ("6645356")).PN.		15:01